REMARKS/ARGUMENTS

Claims 3 and 4, which were withdrawn from consideration, have been canceled without prejudice to filing a divisional application.

Claims 1 and 2 remain unamended. Claim 5 adds the materials of the face body to claim 1. Claim 6 adds a dimension to the first metal layer as being at most slightly wider in any direction on the bonding pad than the paste body. This can be seen in the layer 41 of Figs. 1C and 1F where the first metal layer 41 is wider by the thickness of the side 42 of the first metal layer and in the layer 41 of Figs. 2C and 2F where the paste body and the first metal layer are of the same width.

Claims 1 and 2 were rejected as anticipated by Yamaji. Reconsideration of this rejection is requested.

As to claim 1, a lead portion of conductive paste is filled in the body of the bump. The second metal layer is formed on the conductive paste body and over the bump portion enabling a thin conductive bump to be provided.

The resulting thinness permitted by the sandwiching of the conductive paste between the first and second metal layers in claim 1 distinguishes from the considerably thicker bump portion of Yamaji. This results in a decrease in the profile of the semiconductor device with its conductive bump.

The particular thermosetting resin with conductive filler of dependent claim 5 also distinguishes from Yamaji under Sections 102 and 103.

With respect to new claim 6, a particular size first metal layer 41 in Applicant's embodiments in Figs. 1 and 2 is distinguishable from the first metal layer 4 in all of the embodiments of Yamaji, as Yamaji's first metal layer extends a considerable distance away from the conductive paste body in a width direction.

Applicant's smaller size first metal layer saves material and also is easy to manufacture by the technique disclosed, in that the metal layer can be applied after the photoresist layer 2 is applied, whereas in Yamaji, with the wider first layer 4, the metal layer must be applied before the covering layer 5 of resin. Thus, the difference in applicant's bump structure enables fabrication using a different method and a different sequence of steps. Claim 6 is allowable over Yamaji.

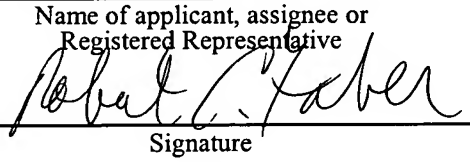
Applicant's claim 2 is allowable because Yamaji does not describe a metal layer having a peripheral portion confining a recess for the paste body. The Examiner refers to Fig. 2B of Yamaji. But, the first metal plate 4 in Yamaji does not itself have a peripheral portion that extends up as Applicant claims "a peripheral portion extending from said base portion in a transverse direction relative to said base portion and cooperating with said base portion to confine a recess" for the conductive paste body. There is no suggestion of Applicant's first metal layer including not only a base portion 41 but also a peripheral portion 42 confining the recess 40 in which the paste body 5 is disposed. Claim 2 is neither anticipated by nor obvious over Yamaji.

For the reasons discussed above, claims 1, 2, 5 and 6 are allowable.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on December 29, 2005:

Robert C. Faber

Name of applicant, assignee or Registered Representative

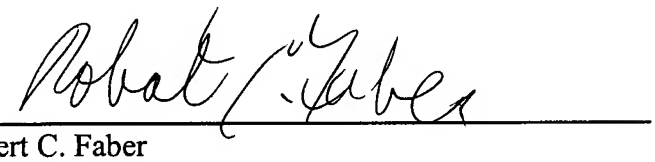


Signature

December 29, 2005

Date of Signature

Respectfully submitted,



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